



40V N-CHANNEL ENHANCEMENT MODE MOSFET POWERDI

Product Summary

| BV _{DSS} | R _{DS(ON)} max | I _D T _C = +25°C (Note 9) |
|-------------------|--|--|
| 40V | $1.8m\Omega$ @ $V_{GS} = 10V$ | 100A |
| | $3.1 \text{m}\Omega$ @ $V_{GS} = 4.5 \text{V}$ | 100A |

Features

- 100% Unclamped Inductive Switching Ensures More Reliable and Robust End Application
- Thermally Efficient Package-Cooler Running Applications
- High Conversion Efficiency
- Low R_{DS(ON)} Minimizes On State Losses
- <1.1mm Package Profile Ideal for Thin Applications
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Description and Applications

This MOSFET has been designed to minimize the on-state resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Engine Management Systems
- Body Control Electronics
- DC-DC Converters

Mechanical Data

- Case: PowerDI5060-8 (Type K)
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Finish Matte Tin Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 ⁽³⁾
- Weight: 0.097 grams (Approximate)

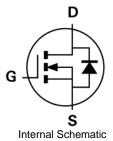


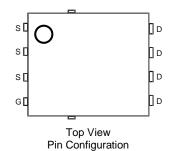
Top View



PowerDI5060-8 (Type K)







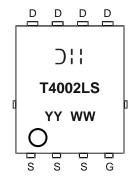
Ordering Information (Note 4)

| Part Number | Case | Packaging |
|---------------|------------------------|---------------------|
| DMT4002LPS-13 | PowerDI5060-8 (Type K) | 2,500 / Tape & Reel |

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



T4002LS = Product Type Marking Code
YYWW = Date Code Marking
YY = Last Two Digits of Year (ex: 16 = 2016)
WW = Week Code (01 to 53)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Units | |
|--|----------------------------------|-----------------|------------|----|
| Drain-Source Voltage | V_{DSS} | 40 | V | |
| Gate-Source Voltage | | V_{GSS} | ±20 | V |
| Continuous Drain Current, V _{GS} = 10V (Notes 6, 9) | $T_C = +25$ °C $T_C = +70$ °C | I _D | 100 100 | А |
| Pulsed Drain Current (10µs pulse, duty cycle = 1%) | | I _{DM} | 200 | Α |
| Continuous Body Diode Forward Current (Note 6) | T _C = +25°C | I _S | 85 | Α |
| Avalanche Current, L = 0.1mH | | I _{AS} | 48 | Α |
| Avalanche Energy, L = 0.1mH | | E _{AS} | 115 | mJ |

Thermal Characteristics

| Characteristic | Symbol | Value | Units |
|--|-----------------------------------|-------------|-------|
| Total Power Dissipation (Note 5) | P_{D} | 2.3 | W |
| Thermal Resistance, Junction to Ambient (Note 5) | $R_{\theta JA}$ | 55 | °C/W |
| Total Power Dissipation (Note 6) | P_{D} | 104 | W |
| Thermal Resistance, Junction to Case (Note 6) | $R_{\theta JC}$ | 1.2 | °C/W |
| Operating and Storage Temperature Range | T _J , T _{STG} | -55 to +150 | °C |

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Min | Тур | Max | Unit | Test Condition | |
|--|---------------------|-----|-------|------|-------|---|--|
| OFF CHARACTERISTICS (Note 7) | | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | 40 | _ | _ | V | $V_{GS} = 0V, I_D = 250\mu A$ | |
| Zero Gate Voltage Drain Current | I _{DSS} | _ | _ | 1 | μΑ | $V_{DS} = 32V$, $V_{GS} = 0V$ | |
| Gate-Source Leakage | I _{GSS} | _ | _ | ±100 | nA | $V_{GS} = \pm 20V, V_{DS} = 0V$ | |
| ON CHARACTERISTICS (Note 7) | | | l. | l . | l. | , == | |
| Gate Threshold Voltage | V _{GS(TH)} | 1 | _ | 3 | V | $V_{DS} = V_{GS}, I_{D} = 250 \mu A$ | |
| Static Drain-Source On-Resistance | | _ | 1.3 | 1.8 | mΩ | $V_{GS} = 10V, I_D = 25A$ | |
| Static Drain-Source On-Resistance | R _{DS(ON)} | _ | 2 | 3.1 | 11177 | $V_{GS} = 4.5V, I_D = 25A$ | |
| Diode Forward Voltage | V_{SD} | _ | _ | 1.2 | V | $V_{GS} = 0V, I_{S} = 20A$ | |
| DYNAMIC CHARACTERISTICS (Note 8) | | | | | | | |
| Input Capacitance | C _{iss} | _ | 6771 | _ | | $V_{DS} = 20V$, $V_{GS} = 0V$, $f = 1MHz$ | |
| Output Capacitance | Coss | _ | 2165 | _ | pF | | |
| Reverse Transfer Capacitance | C_{rss} | _ | 176 | _ | | | |
| Gate Resistance | R _G | _ | 0.85 | _ | Ω | $V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$ | |
| Total Gate Charge (V _{GS} = 10V) | Q_{g} | - | 116.1 | _ | | V _{DD} = 20V, I _D = 25A, V _{GS} = 10V | |
| Total Gate Charge (V _{GS} = 4.5V) | Q_g | 1 | 55.2 | _ | nC | | |
| Gate-Source Charge | Q_{gs} | _ | 20.3 | _ | 110 | | |
| Gate-Drain Charge | Q_{gd} | _ | 22.7 | _ | | | |
| Turn-On Delay Time | t _{D(ON)} | _ | 11.4 | _ | | $V_{DD} = 20V, V_{GS} = 10V,$ $I_{D} = 25A, R_{G} = 3\Omega$ | |
| Turn-On Rise Time | t _R | _ | 22.9 | _ | l | | |
| Turn-Off Delay Time | t _{D(OFF)} | _ | 62.5 | _ | ns | | |
| Turn-Off Fall Time | t _F | _ | 28 | _ | | | |
| Reverse Recovery Time | t _{RR} | _ | 58.6 | _ | ns | L_ 25A d:/dt 100A/us | |
| Reverse Recovery Charge | Q _{RR} | _ | 107 | _ | nC | I _F = 25A, di/dt = 100A/μs | |

Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.

9. Package limited.

^{6.} Thermal resistance from junction to soldering point (on the exposed drain pad).

^{7.} Short duration pulse test used to minimize self-heating effect.

^{8.} Guaranteed by design. Not subject to product testing.

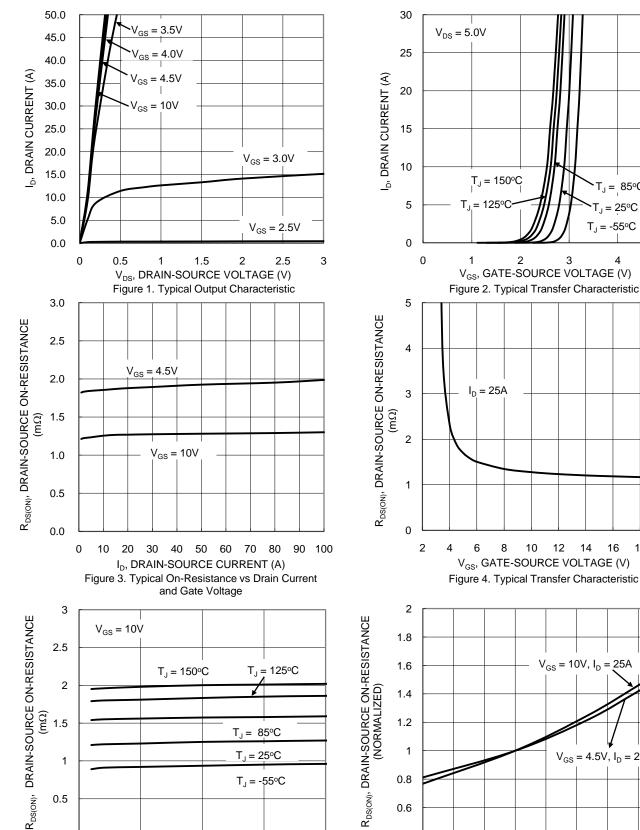
 $T_J = 85^{\circ}C$

 $T_{J} = 25^{\circ}C$

5

 $T_J = -55^{\circ}C$





I_D, DRAIN CURRENT (A) Figure 5. Typical On-Resistance vs Drain Current and Temperature

10

 $T_{J} = -55^{\circ}C$

15

T_J, JUNCTION TEMPERATURE (°C) Figure 6. On-Resistance Variation with Temperature

50

75

10 12 14

 $V_{GS} = 10V, I_D =$

 $V_{GS} = 4.5V, I_{D} = 25A$

16 18 20

8.0

0.6

0.4

-50

-25

0

25

100 125 150

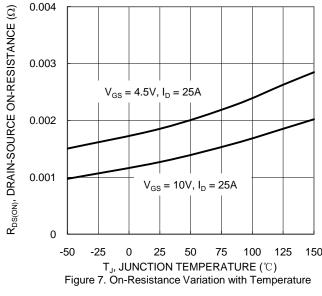
0.5

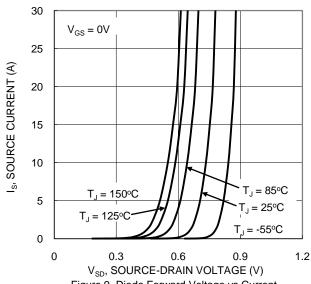
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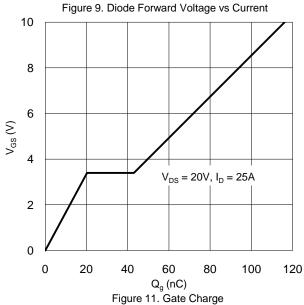
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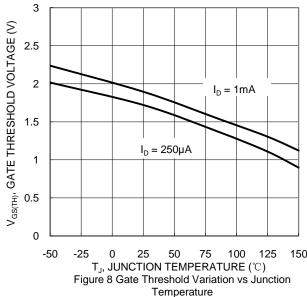
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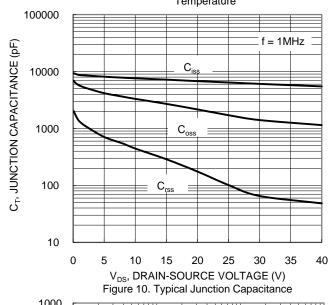


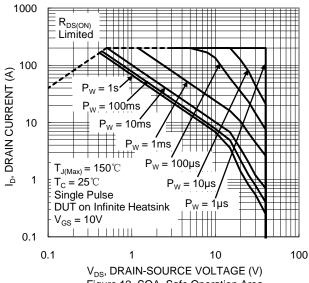














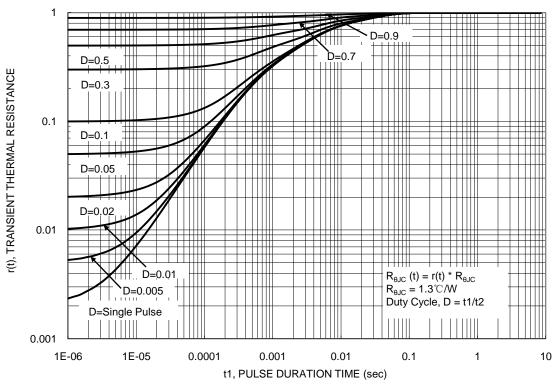


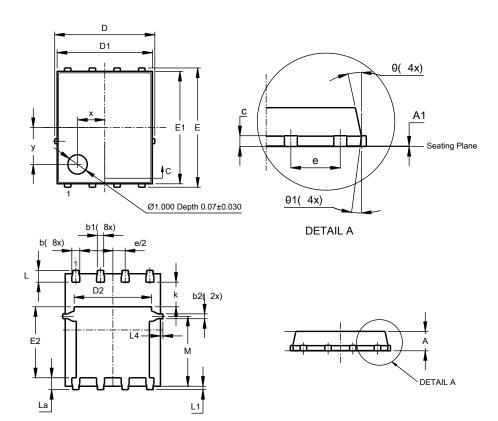
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI5060-8 (Type K)

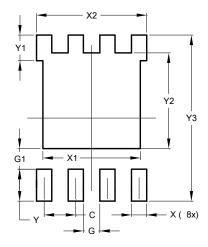


| PowerDI5060-8 | | | | | |
|----------------------|-------|---------|-------|--|--|
| (Type K) | | | | | |
| Dim | Min | Max | Тур | | |
| Α | 0.90 | 1.10 | 1.00 | | |
| A1 | 0 | 0.05 | 0.02 | | |
| b | 0.33 | 0.51 | 0.41 | | |
| b1 | 0.300 | 0.366 | 0.333 | | |
| b2 | 0.20 | 0.35 | 0.25 | | |
| С | 0.23 | 0.33 | 0.277 | | |
| D | 5 | .15 BS0 |) | | |
| D1 | 4.85 | 4.95 | 4.90 | | |
| D2 | - | - | 3.98 | | |
| E | 6 | .15 BS0 | 2 | | |
| E1 | 5.75 | 5.85 | 5.80 | | |
| E2 | 3.56 | 3.725 | 3.66 | | |
| Е | 1 | .27BSC |) | | |
| k | - | - | 1.27 | | |
| L | 0.51 | 0.71 | 0.61 | | |
| La | 0.51 | 0.675 | 0.61 | | |
| L1 | 0.05 | 0.20 | 0.175 | | |
| L4 | - | - | 0.125 | | |
| М | 3.50 | 3.71 | 3.605 | | |
| Х | - | - | 1.400 | | |
| у | - | - | 1.900 | | |
| θ | 10° | 12° | 11° | | |
| θ1 | 6° | 8° | 7° | | |
| All Dimensions in mm | | | | | |

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI5060-8 (Type K)



| Dimensions | Value (in mm) | | |
|------------|------------------|--|--|
| С | 1.270 | | |
| G | 0.660 | | |
| G1 | 0.820 | | |
| X | 0.610 | | |
| X1 | 3.910 | | |
| X2 | 4.420 | | |
| Υ | 1.270 | | |
| Y1 | 1.020 | | |
| Y2 | 3.810 | | |
| Y3 | 6.610 | | |



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